

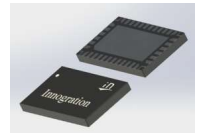


DC-1.7GHz, 8W, 28V LDMOS Fully matched PA Module

Description

The IMEH0017-8 is a 8-watt ,single stage integrated Power Amplifier Module, designed for broad band applications, with frequencies from DC to 1.7GHz. The module is 50 Ω input/output matched and requires minimal external components.

The module implements distributed power amplifier in form of multi chips, housed in cost effective plastic open cavity package, offers a much lower cost than traditional MMIC solutions.



V_{ds}=28V, I_{dq}=150mA, CW

Parameter	30MHz	0.2GHz	0.5GHz	0.8GHz	1.0GHz	1.2GHz	1.5GHz	1.7GHz	Units
Linear Gain	22.5	21.7	20.9	20.0	19.9	18.8	20.3	20.3	dB
P _{out} @P _{in} =22dBm	9.8	9.8	10.2	9.2	9.0	9.6	10.1	8.6	W
Gain@P _{in} =22dBm	18.7	17.9	18.1	17.7	17.5	17.8	18.0	17.4	dB
Eff@ P _{in} =22dBm	77	70	57	45	39	40	47	47	%

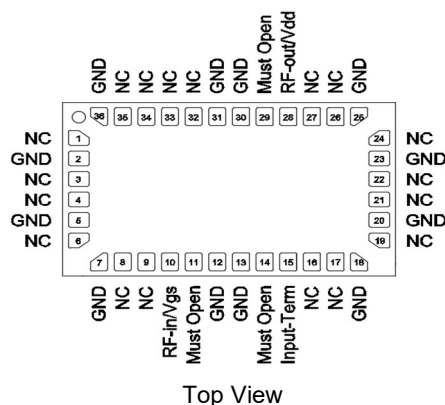
Product Features

- Operating Frequency Range: DC-1.7GHz
- Operating Drain Voltage: +28 V
- 50 Ω Input/Output
- P_{sat}: ≥8W
- Small signal gain:>18dB, Power gain:>16dB
- Minimum efficiency:>35%
- 6x10 mm Surface Mount Package
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC
- Much lower cost than GaN-based ultrawide band PA , due to LDMOS technology used

Applications

- Ultra Broadband Amplifiers
- Fiber Drivers
- Test Instrumentation
- EMC Amplifier Drivers
- 2-way Radios

Pin Configuration and Description





Pin No.	Symbol	Description
28	RFout/Vdd	Transistor 1, Drain Bias & RF Output
10	RFin/Vgs	Transistor 1, RF Input & Gate Bias
15	Input-Term	Transistor 1, Input 50 ohm term
Others	NC	No connection
11, 14, 29	Must Open	Keep the pin open, no GND
2,5,7,12,13,16,20,23,25, 30, 31,36 Package Base	GND	DC/RF Ground. Must be soldered to EVB ground plane over array of vias for thermal and RF performance. Solder voids under Pkg Base will result in excessive junction temperatures causing permanent damage.

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	65	Vdc
Gate--Source Voltage	V_{GS}	-10 to +10	Vdc
Operating Voltage	V_{DD}	+32	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_c	+150	°C
Operating Junction Temperature	T_j	+200	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_c=87^\circ\text{C}$, $T_j=175^\circ\text{C}$, DC test	$R_{\theta JC}$	2.2	°C/W

Table 3. Electrical Characteristics

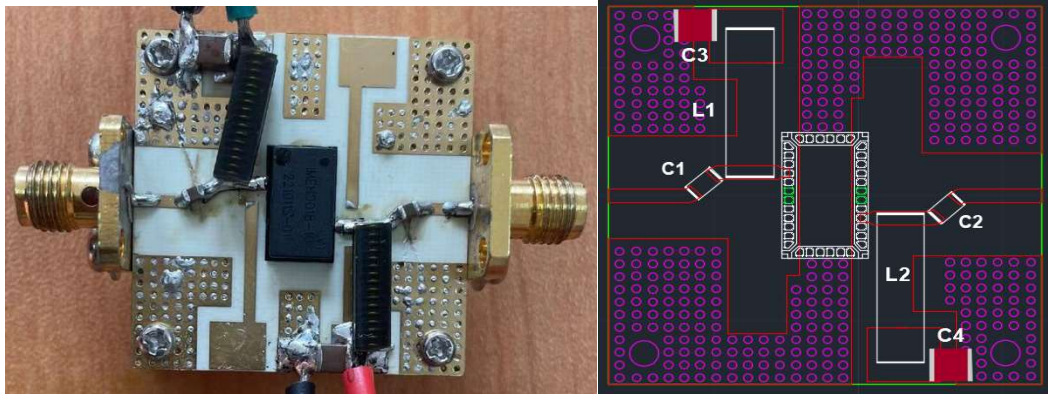
Parameter	Condition	Min	Typ	Max	Unit
Frequency Range		30		1700	MHz
Power Gain @ Psat		16			dB
P_{SAT}		39			dBm
Drain Efficiency @ P_{SAT}		35			%

Unless otherwise noted: $T_A = 25^\circ\text{C}$, $V_{DD} = 28\text{ V}$, Pulse Width=100 us, Duty cycle=10%

Load Mismatch of per Section (On Test Fixture, 50 ohm system): $V_{DD} = 28\text{ V}$, $I_{DQ} = 40\text{ mA}$, $f = 1.6\text{ GHz}$

VSWR 10:1 at Psat pulse CW Output Power	No Device Degradation
---	-----------------------

Reference Circuit of Test Fixture Assembly Diagram



		Part NO.	Vendor
C3,C4	10uF 100V chip Capacitor	C5750X7S2A106M230KB	TDK
C1,C2	50V 1uF Chip Capacitor	GRM21BR71H105KA12L	muRata
L1,L2	1.3 uH 4.2A Inductor	4310LC-132KEC	Coilcraft
PCB	RO4350B,20mil,er=3.48		

TYPICAL CHARACTERISTICS

Figure 1. Network analyzer output S11/S21 (Pin=0dBm)

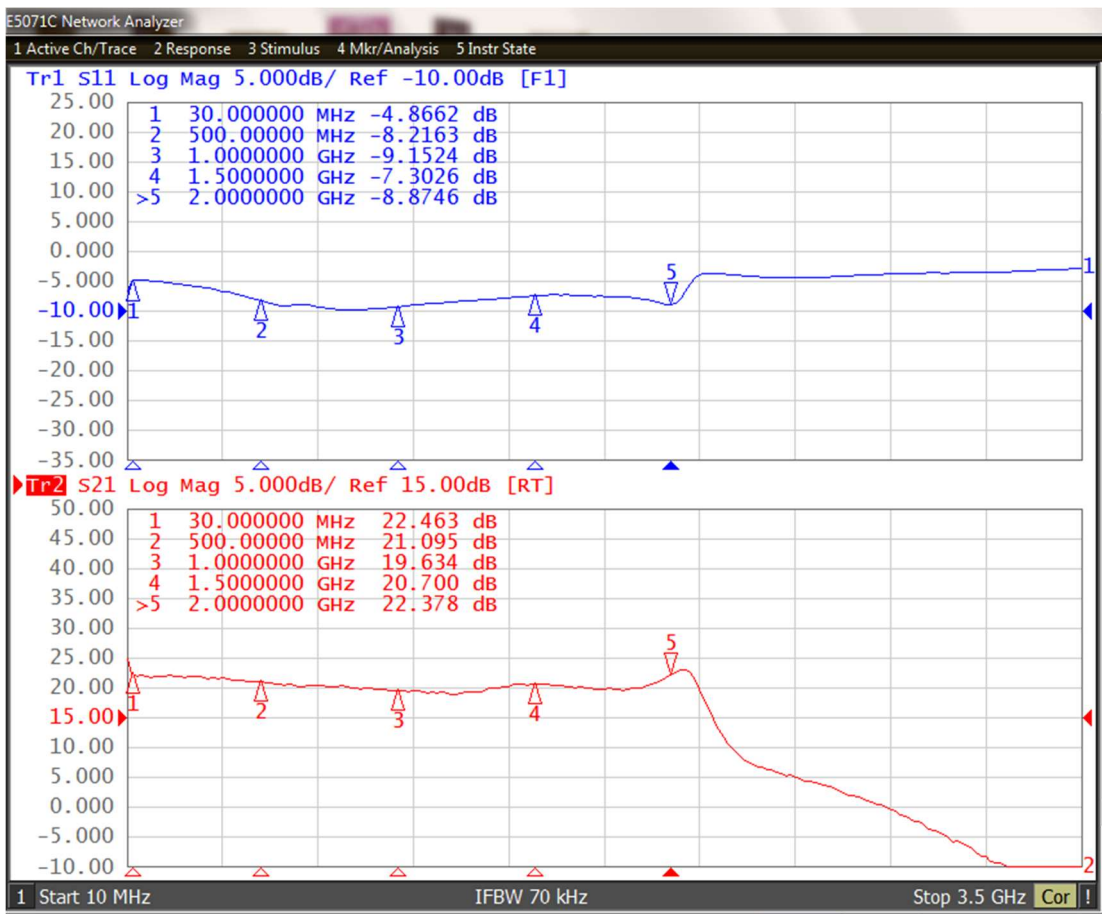
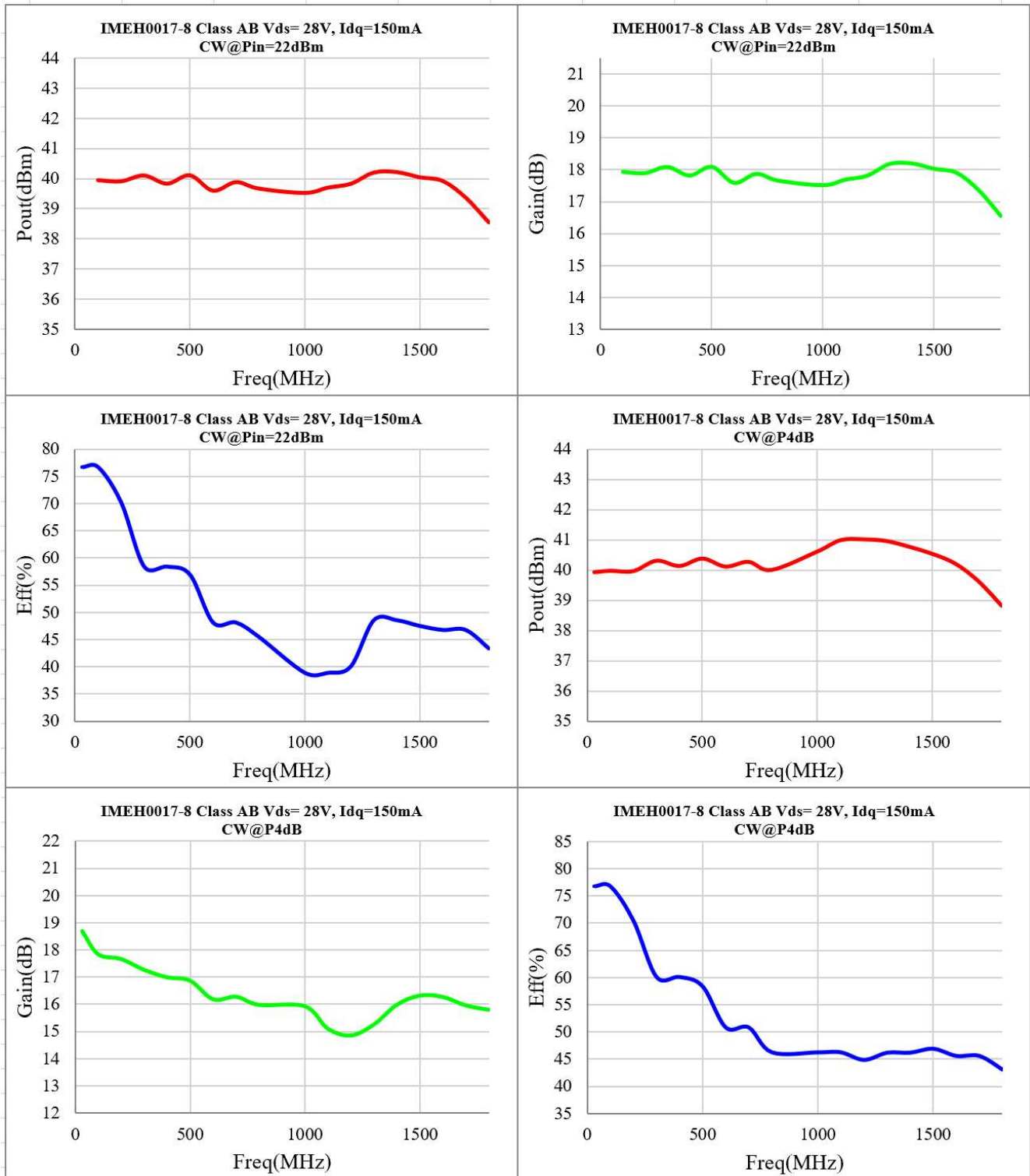


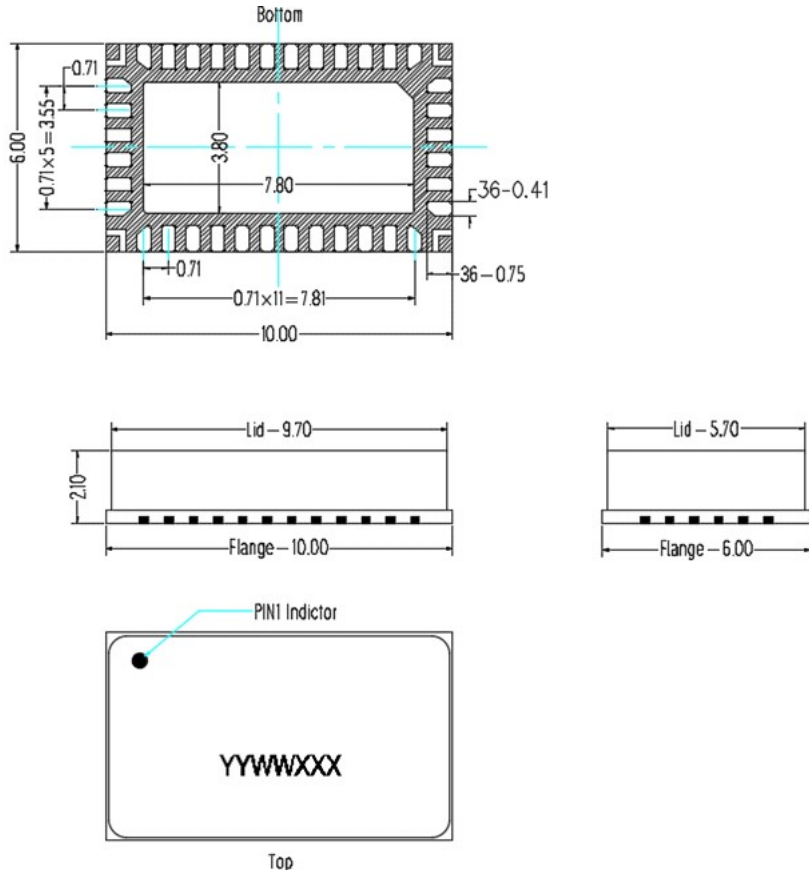


Figure. Power Gain and, efficiency and Pout @Pin=22dBm ,and P4dB vs. Frequency



Package Dimensions

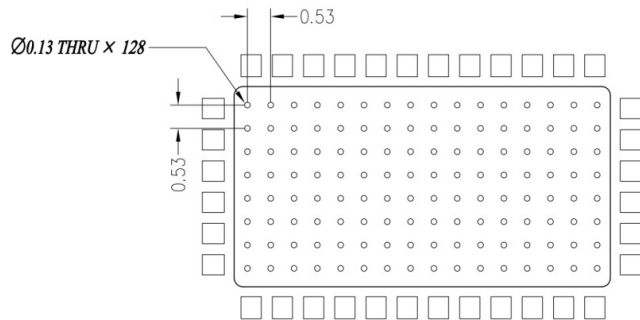
10*6 Plastic Package



Notes:

1. All dimensions are in mm;
2. The tolerances unless specified are ± 0.2 mm.

Mounting Footprint Pattern



Notes:

1. All dimensions are in mm;
2. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. ALL vias are PTH to ground.



Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2022/12/9	Rev 1.0	Production Datasheet

Application data based on ZHH-22-02

Disclaimers

Specifications are subject to change without notice. Innogrations believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Innogrations for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Innogrations . Innogrations makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Innogrations in large quantities and are provided for information purposes only. These values can and do vary in different applications and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Innogrations products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Innogrations product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility. For any concerns or questions related to terms or conditions, pls check with Innogrations and authorized distributors

Copyright © by Innogrations (Suzhou) Co.,Ltd.